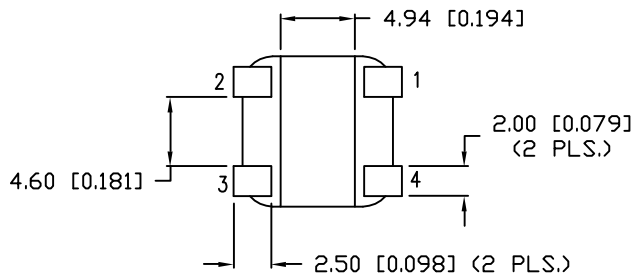
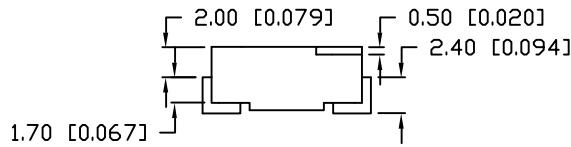
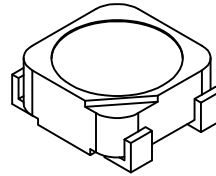
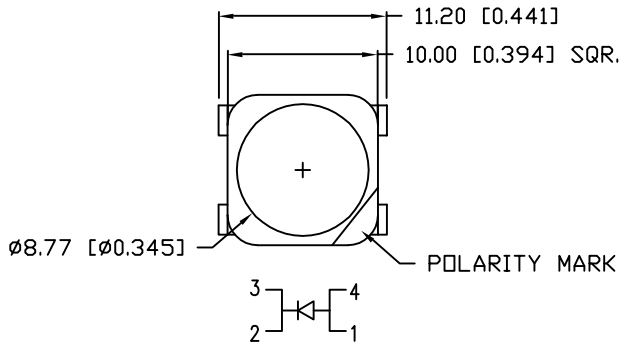


UNCONTROLLED DOCUMENT

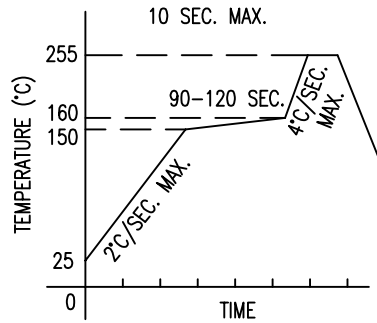
PART NUMBER
SML-LX1110SOC-ATR

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11440.	9.07.07



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=350\text{mA}$

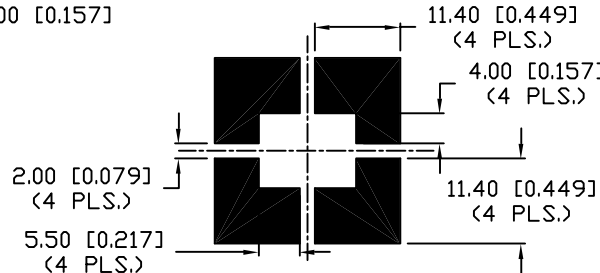
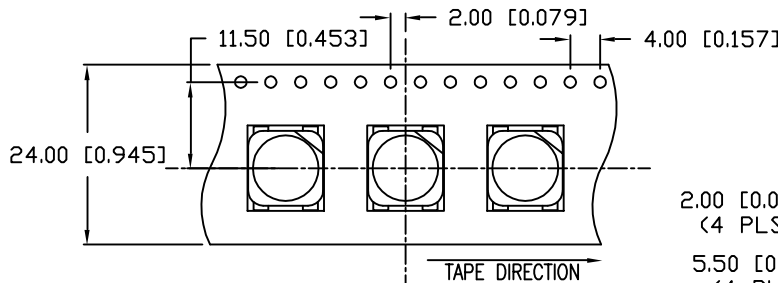
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		620		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		25000		mcd	$I_f=350\text{mA}$
LUMINOUS FLUX		15		lm	$I_f=350\text{mA}$
VIEWING ANGLE		90		2x theta	
EMITTED COLOR:	ORANGE				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	500	mA
STEADY CURRENT	350	mA
POWER DISSIPATION	1.2	W
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

RECOMMENDED SOLDER PAD LAYOUT



NOTES:

1. ANODE TOWARDS TAPE HOLE.



UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV. A PART NUMBER SML-LX1110SOC-ATR

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PLCC-4 SMT LED, HIGH POWER, 620nm SUPER ORANGE,
WITH INTERNAL REFLECTIVE CAVITY.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JD	CHECKED BY:	APPROVED BY:	DATE: 7.11.05
			PAGE: 1 OF 1
			SCALE: N/A